

N05BT1006J

List

List.....	1
Package outline.....	2
Features.....	2
Mechanical data.....	2
Applications.....	2
Maximum ratings	2
Electrical characteristics.....	2
Rating and characteristic curves.....	3
Pinning information.....	4
Marking.....	4
Suggested solder pad layout.....	4
Packing information.....	5
Reel packing.....	6
Suggested thermal profiles for soldering processes.....	6

N05BT1006J

100W Bi-Directional TVS For ESD Protection : 5.0V

Features

- 100Watts peak pulse power ($t_p=8/20\mu s$).
- Protects one data or power line to:
 - IEC 61000-4-2 $\pm 30kV$ (Contact), $\pm 30kV$ (Air).
 - IEC 61000-4-5 (Lightning) 8A (8/20us).
- Lead-free parts meet RoHS requirements.
- Suffix "-H" indicates Halogen-free parts, ex.N05BT1006J-H.

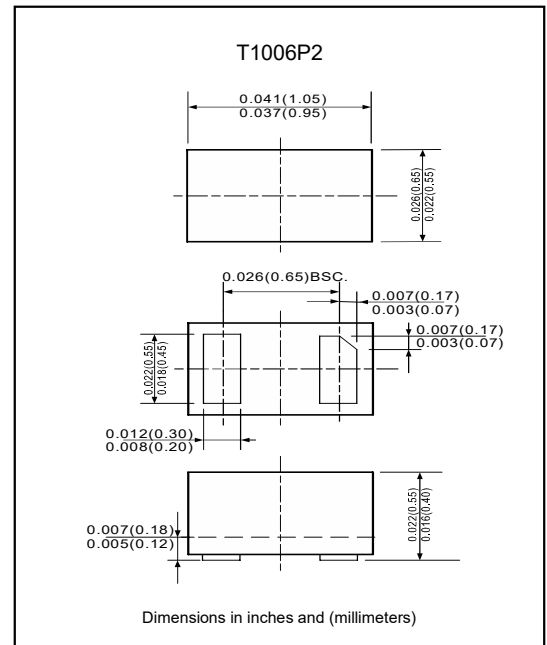
Applications

- Cell phone handsets and accessories.
- Microprocessor based equipment.
- Personal digital assistants (PDA's).
- Notebooks, handhelds and digital cameras.
- Portable instrumentation.
- Peripherals, audio players, keypads, side keys and LCD displays.

Mechanical data

- Epoxy: UL94-V0 rated flame retardant.
- Case: T1006P2 package.

Package outline



Maximum ratings (At $T_A=25^\circ C$ unless otherwise noted)

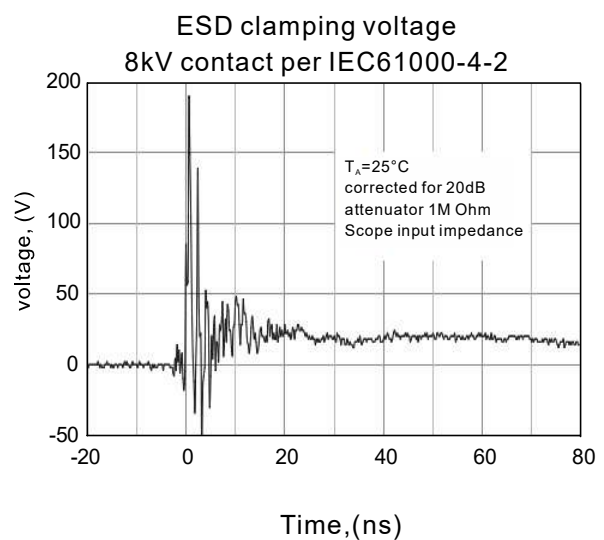
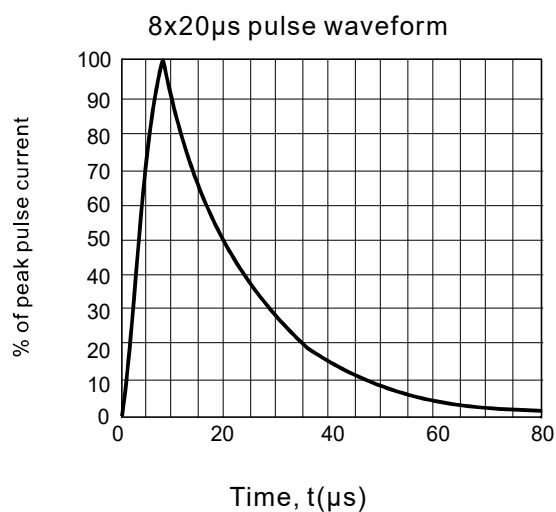
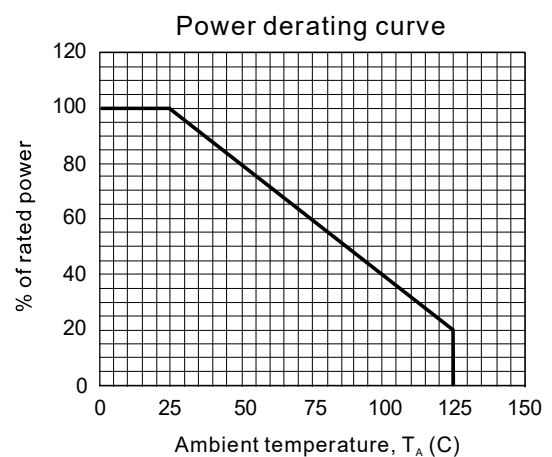
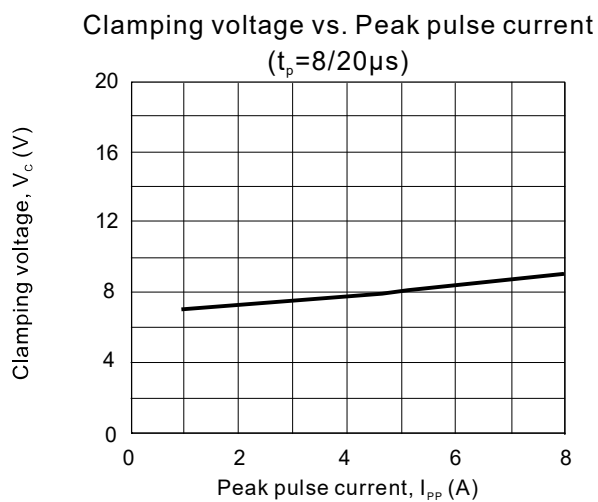
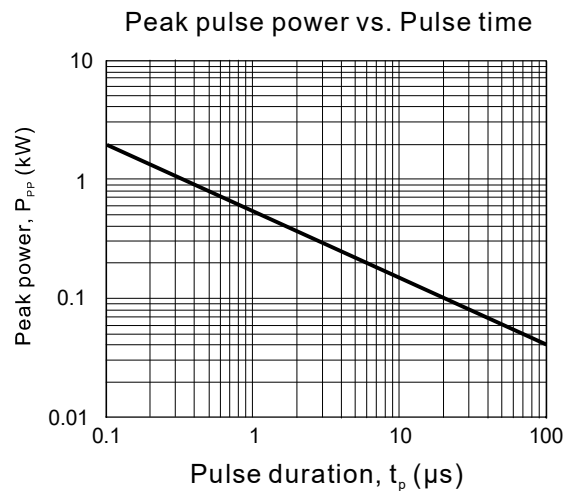
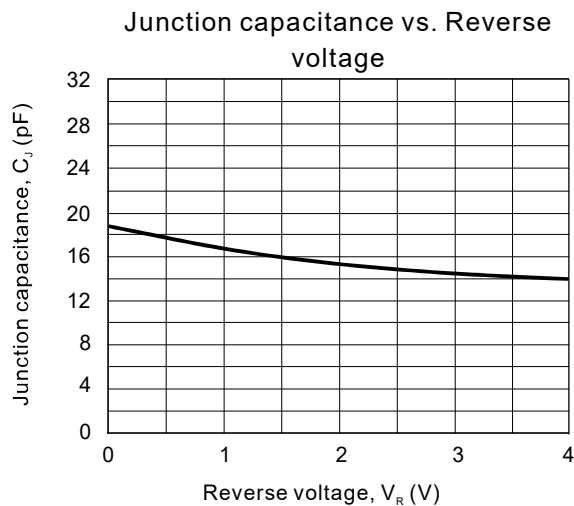
Parameter	Symbol	Value	Unit
Peak pulse power ($t_p=8/20\mu s$)	P_{PP}	100	W
Peak pulse current ($t_p=8/20\mu s$)	I_{PP}	8	A
ESD per IEC 61000-4-2 (Air)	V_{ESD}	± 30	kV
ESD per IEC 61000-4-2 (Contact)			
Junction temperature	T_J	+125	$^\circ C$
Storage temperature	T_{STG}	-55 to +150	$^\circ C$

Electrical characteristics (At $T_A=25^\circ C$ unless otherwise noted)

Parameter	Conditions	Symbol	Min.	Typ.	Max.	Unit
Reverse stand-off voltage		V_{RWM}			5	V
Breakdown voltage	$I_T=1mA$	V_{BR}	6		8	V
Reverse leakage current	$V_{RWM}=5V$	I_R			0.2	μA
Clamping voltage	$I_{PP}=1A, t_p=8/20\mu s$	V_C			8	V
	$I_{PP}=8A, t_p=8/20\mu s$				12.5	
Junction capacitance	$V_R=0V, f=1.0MHz$	C_J		15		pF

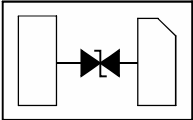
N05BT1006J

Rating and characteristic curves



N05BT1006J

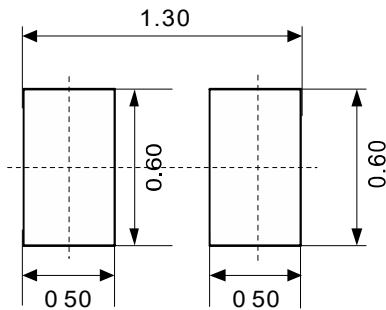
Pinning information

Pin	Simplified outline	Symbol
Bi-Directional		

Marking

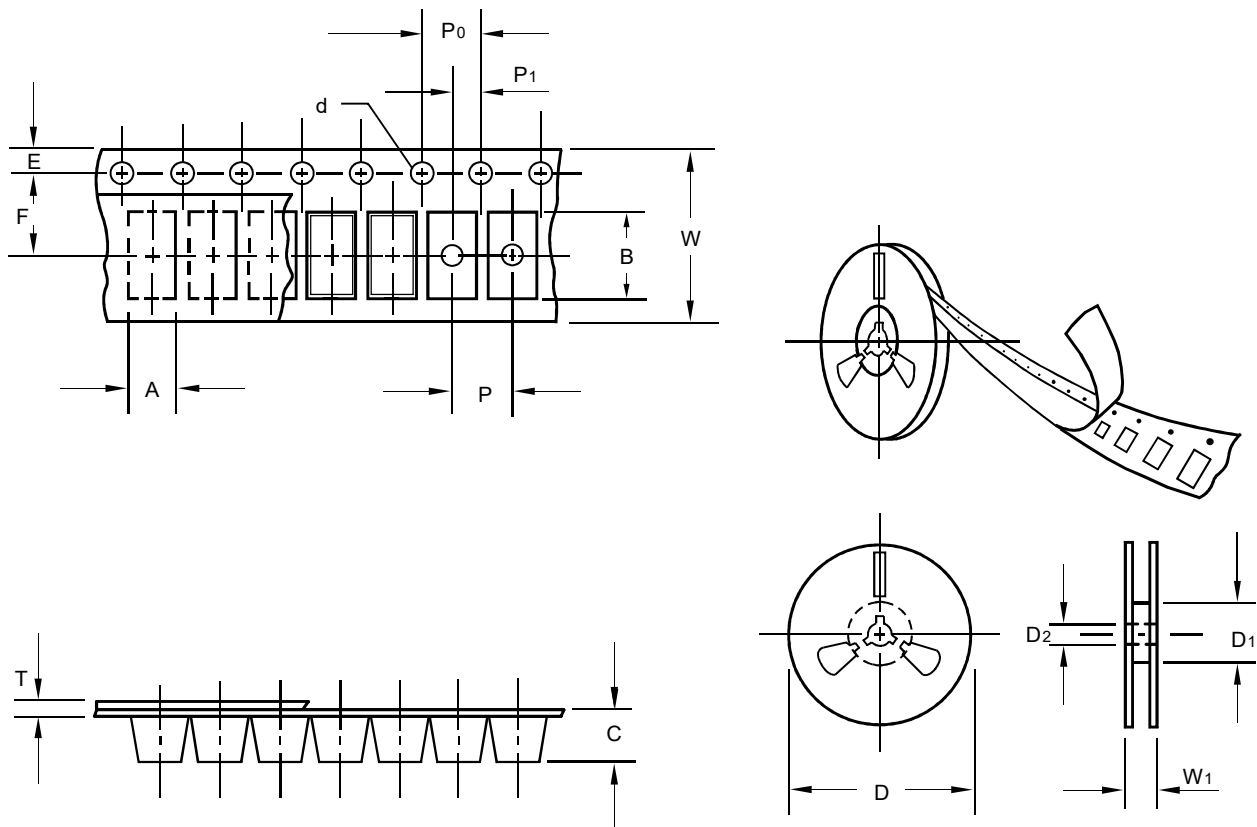
Type number	Marking code
N05BT1006J	PB

Suggested solder pad layout



N05BT1006J

Packing information



unit:mm

Item	Symbol	Tolerance	T1006P2
Carrier width	A	0.1	0.66
Carrier length	B	0.1	1.15
Carrier depth	C	0.1	0.66
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D ₁	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D ₁	min	55.00
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	2.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W ₁	1.0	9.50

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

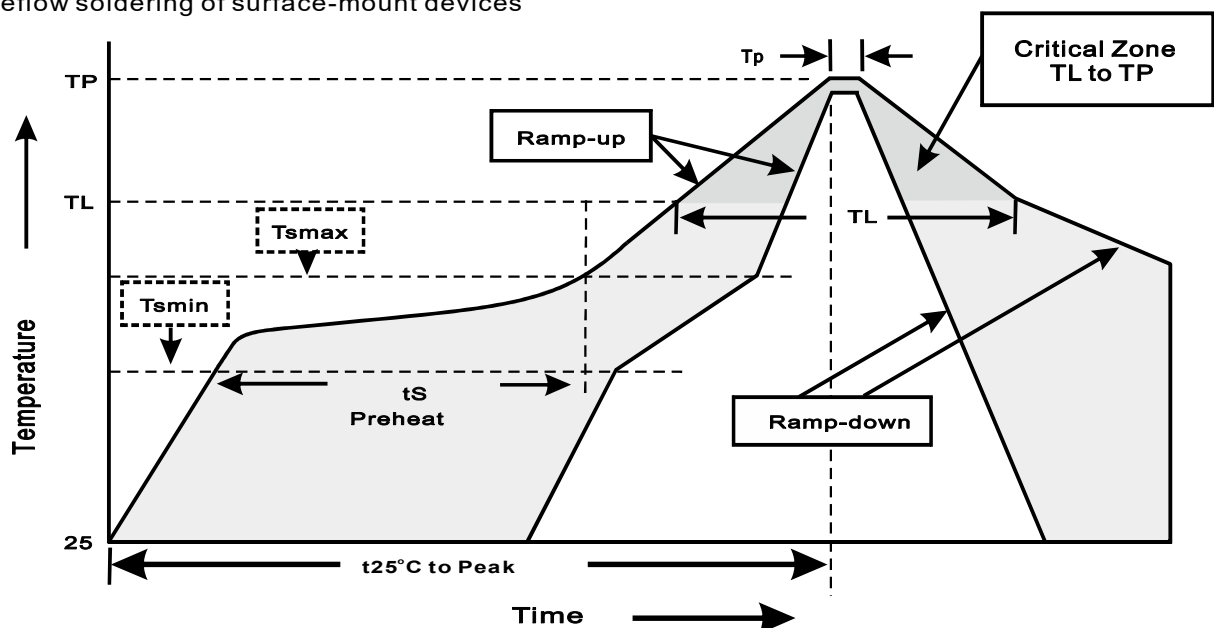
N05BT1006J

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)
T1006P2	7"	10,000	4.0	100,000	183*123*183	178	382*257*387	800,000

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



- 3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	$<3^{\circ}\text{C}/\text{sec}$
Preheat -Temperature Min(T_{smin}) -Temperature Max(T_{smax}) -Time(min to max)(t_s)	150°C 200°C 60~120sec
T_{smax} to T_L -Ramp-upRate	$<3^{\circ}\text{C}/\text{sec}$
Time maintained above: -Temperature(T_L) -Time(t_L)	217°C 60~260sec
Peak Temperature(T_P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t_P)	10~30sec
Ramp-down Rate	$<6^{\circ}\text{C}/\text{sec}$
Time 25°C to Peak Temperature	$<6\text{minutes}$